



172
Docket No.: M4065.0222/P222-B
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Tongbi Jiang

Application No.: 10/667,391

Confirmation No.: 1655

Filed: September 23, 2003

Art Unit: 2812

For: METHOD OF MAKING A CENTER BOND
FLIP CHIP SEMICONDUCTOR CARRIER

Examiner: S. B. Geyer

AMENDMENT AFTER ALLOWANCE UNDER 37 C.F.R. 1.312

MS Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

Prior to issuance of the patent, applicant respectfully requests entry on this amendment under 37 C.F.R. 1.312 for the above-captioned patent application.

Amendments to the Specification begin on page 2 of this paper.

Remarks/Arguments begin on page 3 of this paper.